Papers are solicited in the following themes of interest:

- Technology CAD and benchmarking
- Advanced logic and memory device modeling
- Atomistic material, process, and interconnect simulation
- Compact models for DTCO
- Alternative computing device modeling
- Nanoscale (bio)sensors modeling

New or trending areas include:

- Multi-scale simulation with hybrid techniques
- Advanced packaging and 3D integration modeling
- Thermal modeling
- Low-temperature and quantum device modeling
- Device modeling for photonics
- Device modeling for in-memory and in-sensor computing

Paper Submission

Submission deadline: July 11th
Single submission of final, four-page paper